SCES075D - JUNE 1996 - REVISED DECEMBER 2002

- State-of-the-Art Advanced BiCMOS
 Technology (ABT) Widebus™ Design for
 2.5-V and 3.3-V Operation and Low
 Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- High Drive (-12/12 mA at 3.3-V V_{CC})
- I_{off} and Power-Up 3-State Support Hot Insertion
- Use Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating
- Output Ports Have Equivalent 30-Ω Series Resistors, So No External Resistors Are Required
- Flow-Through Architecture Facilitates
 Printed Circuit Board Layout
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

SN54ALVTHR16245 . . . WD PACKAGE SN74ALVTHR16245 . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)

	_			
1DIR [1	\cup	48	1 <u>0E</u>
1B1 [2		47	1A1
1B2 [3		46] 1A2
GND [4		45	GND
1B3 [5		44] 1A3
1B4 [6		43] 1A4
v _{cc} [7		42] v _{cc}
1B5 [41] 1A5
1B6 [9		40] 1A6
GND [10		39	GND
1B7 [11		38] 1A7
1B8 [12		37	1A8
2B1 [13		36	2A1
2B2	14		35	2A2
GND [15		34	GND
2B3 [16		33	
2B4	17		32	2A4
v _{cc} [18		31	□ v _{cc}
2B5	1			
2B6				2A6
GND [] GND
2B7	1			E
2B8				2 <u>A8</u>
2DIR [24		25	2 <u>OE</u>
				J

description/ordering information

The 'ALVTHR16245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for 2.5-V or 3.3-V V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

ORDERING INFORMATION

TA	PACKAGE [†]		PACKAGE [†] ORDERABLE PART NUMBER	
	SSOP – DL	Tape and reel	SN74ALVTHR16245LR	ALVTHR16245
4000 1- 0500	TSSOP – DGG Tape and reel		SN74ALVTHR16245GR	ALVTHR16245
–40°C to 85°C	TVSOP – DGV	Tape and reel	SN74ALVTHR16245VR	TR245
	VFBGA – GQL Tape and reel		SN74ALVTHR16245KR	TR245
-55°C to 125°C	CFP – WD	Tube	SNJ54ALVTHR16245W	SNJ54ALVTHR16245W

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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description/ordering information (continued)

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

All outputs are designed to sink up to 12 mA, and include equivalent $30-\Omega$ resistors to reduce overshoot and undershoot.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN74ALVTHR16245 . . . GQL PACKAGE (TOP VIEW)

1 2 3 4 5 6 000000 000000 В 000000 С 000000 CARGE PHE O O Е \bigcirc F 000000 G 000000 Н 000000 J 000000 Κ

terminal assignments

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1OE
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	Vcc	Vcc	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	VCC	V _{CC}	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2OE

NC - No internal connection

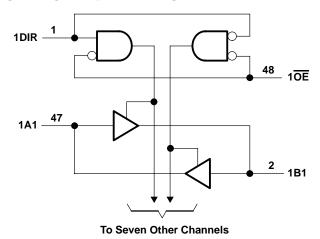
FUNCTION TABLE (each 8-bit section)

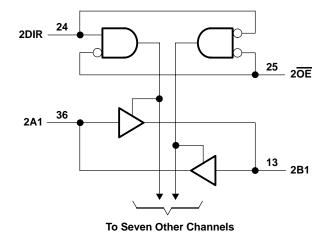
INP	UTS	OPERATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation



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logic diagram (positive logic)





Pin numbers shown are for the DGG, DGV, DL, and WD packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output current in the low state, IO: SN54ALVTHR16245	96 mA
SN74ALVTHR16245	
Output current in the high state, IO: SN54ALVTHR16245	
SN74ALVTHR16245	
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	70°C/W
DGV package	58°C/W
DL package	63°C/W
GQL package	42°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions, $V_{\mbox{\footnotesize{CC}}}$ = 2.5 V \pm 0.2 V (see Note 3)

			SN54A	LVTHR	16245	SN74A	LVTHR1	16245	UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	UNII	
Vcc	Supply voltage		2.3		2.7	2.3		2.7	V
VIH	V _{IH} High-level input voltage		1.7	,	7	1.7			V
V _{IL}	Low-level input voltage			Z	0.7			0.7	V
VI	Input voltage		0	Vcc	5.5	0	VCC	5.5	V
loh	High-level output current			1	-6			-8	mA
loL	Low-level output current			5	6			12	mA
Δt/Δν	Input transition rise or fall rate Outputs enabled		70,	7	10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200			200			μs/V
T _A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

recommended operating conditions, $V_{\mbox{\footnotesize{CC}}}$ = 3.3 V \pm 0.3 V (see Note 3)

			SN54A	LVTHR	16245	SN74A	LVTHR1	16245	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Vcc	Supply voltage		3		3.6	3		3.6	V
VIH	High-level input voltage		2		1	2			V
V _{IL}	Low-level input voltage			7/2	0.8			8.0	V
VI	Input voltage		0	Vcc	5.5	0	VCC	5.5	V
loн	High-level output current			1	-8			-12	mA
l _{OL}	Low-level output current			5	8			12	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	/O ₂	7	10			10	ns/V
Δt/ΔV _{CC}	CC Power-up ramp rate		200			200			μs/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted)

-	ADAMETED	TEST CO	TEST CONDITIONS		ALVTHR	16245	SN74	ALVTHR	16245	LINUT	
Ρ/	ARAMETER	lesi co	SNULLIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT	
VIK		V _{CC} = 2.3 V,	I _I = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0	.2		VCC-0	.2			
Vон		V _{CC} = 2.3 V	$I_{OH} = -6 \text{ mA}$	1.7						V	
		vCC = 2.3 v	$I_{OH} = -8 \text{ mA}$				1.7				
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	$I_{OL} = 100 \mu A$			0.2			0.2		
VOL		V _{CC} = 2.3 V	$I_{OL} = 6 \text{ mA}$			0.7				V	
		VCC = 2.3 V	$I_{OL} = 12 \text{ mA}$						0.7		
	Control inputs	$V_{CC} = 2.7 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1		
	Control inputs	$V_{CC} = 0 \text{ or } 2.7 \text{ V},$	V _I = 5.5 V			10			10		
lį			V _I = 5.5 V		<u>\$</u> 20				20	μΑ	
	A or B ports	V _{CC} = 2.7 V	$V_I = V_{CC}$		Š	1			1		
			V _I = 0		200	- 5			– 5		
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V		1/				±100	μΑ	
I _{BHL} ‡		$V_{CC} = 2.3 \text{ V},$	V _I = 0.7 V		115			115		μΑ	
IBHH		$V_{CC} = 2.3 \text{ V},$	V _I = 1.7 V	20.	– 10			-10		μΑ	
IBHLC	, ¶	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	300			300			μΑ	
Івнно	o [#]	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	-300			-300			μΑ	
{IEX}		$V{CC} = 2.3 \text{ V},$	V _O = 5.5 V			125			125	μΑ	
IOZ(PI	U/PD) [☆]	$V_{CC} \le 1.2 \text{ V}, V_{O} = \frac{0.5}{\text{OE}} \text{ V}$ V _I = GND or V _{CC} , $\overline{\text{OE}}$ =	′ to V _{CC} , don't care			±100			±100	μΑ	
		V _{CC} = 2.7 V,	Outputs high		0.04	0.1		0.04	0.1		
Icc		$I_O = 0$,	Outputs low		2.5	4.5		2.5	4.5	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		0.04	0.1		0.04	0.1		
Ci		V _{CC} = 2.5 V,	V _I = 2.5 V or 0		3.5			3.5		pF	
C _{io}		$V_{CC} = 2.5 \text{ V},$	V _O = 2.5 V or 0		8			8		pF	

[†] All typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. ‡ The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to VCC and then lowering it to VIH min.

[¶] An external driver must source at least IBHLO to switch this node from low to high.

[#] An external driver must sink at least I_{BHHO} to switch this node from high to low.

Current into an output in the high state when VO > VCC

^{*}High-impedance state during power up or power down

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

	DAMETER	TEST CONDITIONS		SN54A	ALVTHR	16245	SN74/	\LVTHR1	16245	UNIT	
Ρ/	ARAMETER	l lesi c	ONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII	
٧ıK		V _{CC} = 3 V,	I _I = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0	.2		VCC-0	.2			
Vон		V _{CC} = 3 V	$I_{OH} = -8 \text{ mA}$	2						V	
		VCC = 3 V	$I_{OH} = -12 \text{ mA}$				2				
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OL} = 100 μA			0.2			0.2		
VOL		V _{CC} = 3 V	$I_{OL} = 8 \text{ mA}$			0.8				V	
		VCC = 3 V	I _{OL} = 12 mA						8.0		
	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1		
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V			10			10		
II			V _I = 5.5 V			<u>2</u> 0			20	μΑ	
	A or B ports	V _{CC} = 3.6 V	VI = VCC		Ś	1			1		
			V _I = 0		24	-5			– 5		
I _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V		7				±100	μΑ	
I _{BHL} ‡		$V_{CC} = 3 V$,	V _I = 0.8 V	75	3		75			μΑ	
IBHH		V _{CC} = 3 V,	V _I = 2 V	-75	<u> </u>		-75			μΑ	
IBHLC		$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	500			500			μΑ	
Івнно) [#]	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	-500			-500			μΑ	
IEX		$V_{CC} = 3 V$,	V _O = 5.5 V			125			125	μΑ	
IOZ(PI	J/PD) [☆]	$V_{CC} \le 1.2 \text{ V}, V_{O} = \underline{0.5} \text{ V}$ $V_{I} = \text{GND or } V_{CC}, \overline{\text{OE}} = \underline{0.5} \text{ V}$	V to V _{CC} , = don't care			±100			±100	μΑ	
		V _{CC} = 3.6 V,	Outputs high		0.07	0.1		0.07	0.1		
ICC		$I_O = 0$,	Outputs low		3.5	5		3.5	5	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		0.07	0.1		0.07	0.1		
∆ICC□	l	$V_{CC} = 3 \text{ V to } 3.6 \text{ V, One}$ Other inputs at V_{CC} or				0.4			0.4	mA	
Ci		V _{CC} = 3.3 V,	V _I = 3.3 V or 0		3.5			3.5		pF	
C _{io}		V _{CC} = 3.3 V,	V _O = 3.3 V or 0		8			8		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

[¶] An external driver must source at least I_{BHLO} to switch this node from low to high.

[#] An external driver must sink at least IBHHO to switch this node from high to low.

 $[\]parallel$ Current into an output in the high state when $V_O > V_{CC}$

^{*}High-impedance state during power up or power down

[☐] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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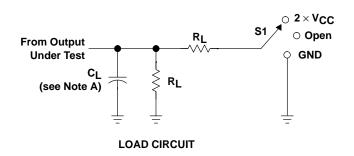
switching characteristics over recommended operating free-air temperature range, C_L = 30 pF, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	SN54ALV	THR16245	SN74ALV	THR16245	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	ONIT
t _{PLH}	A or B	B or A	0.5	4.3	0.5	4.3	ns
t _{PHL}	AOIB	BULK	0.5	3.7	0.5	3.7	115
^t PZH	ŌĒ	A or B	1.8	5.6	1.8	5.6	ns
^t PZL	OE	AOIB	1.6	4.7	1.6	4.7	115
^t PHZ	ŌĒ	A or B	1.7	5	1.7	5	ns
t _{PLZ}	OE .	7010	1.4	4.4	1.4	4.4	115

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

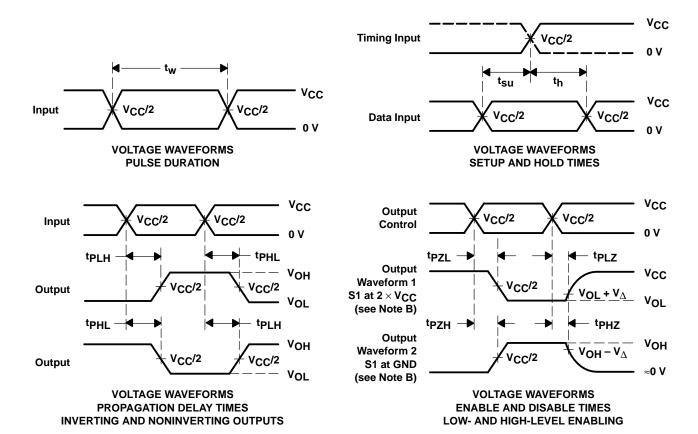
PARAMETER	FROM	то	SN54ALV	THR16245	SN74ALV	THR16245	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	ONIT
t _{PLH}	A or B	B or A	0.5	3.7	0.5	3.7	ns
^t PHL	AOIB	BULK	0.5	3.9	0.5	3.9	115
^t PZH	ŌĒ	A or B	1.3	5.2	1.3	5.2	ns
^t PZL	OE	AOIB	1.3	4	1.3	4	115
^t PHZ	ŌĒ	A or B	2	5.1	2	5.1	ns
t _{PLZ}	OL	AOID	1.5	4.8	1.5	4.8	113

PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
t _{PLZ} /t _{PZL}	2×V _{CC}
tPHZ/tPZH	GND

V _{CC}	CL	RL	$v_{\scriptscriptstyle\Delta}$
2.5 V ±0.2 V	30 pF	500 Ω	0.15 V
3.3 V ±0.3 V	50 pF	500 Ω	0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Ω} = 50 Ω , $t_{f} \leq$ 2 ns, $t_{f} \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
74ALVTHR16245ZQLR	LIFEBUY	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	TR245	
SN74ALVTHR16245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTHR16245	Samples
SN74ALVTHR16245GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTHR16245	Samples
SN74ALVTHR16245LR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVTHR16245	Samples
SN74ALVTHR16245VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TR245	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

6-Feb-2020

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PACKAGE MATERIALS INFORMATION

www.ti.com 12-Feb-2019

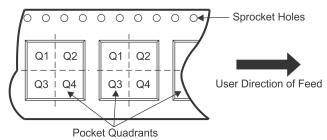
TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVTHR16245ZQLR	BGA MI CROSTA R JUNI OR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1
SN74ALVTHR16245GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ALVTHR16245LR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ALVTHR16245VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ALVTHR16245ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	350.0	350.0	43.0
SN74ALVTHR16245GR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ALVTHR16245LR	SSOP	DL	48	1000	367.0	367.0	55.0
SN74ALVTHR16245VR	TVSOP	DGV	48	2000	367.0	367.0	38.0

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

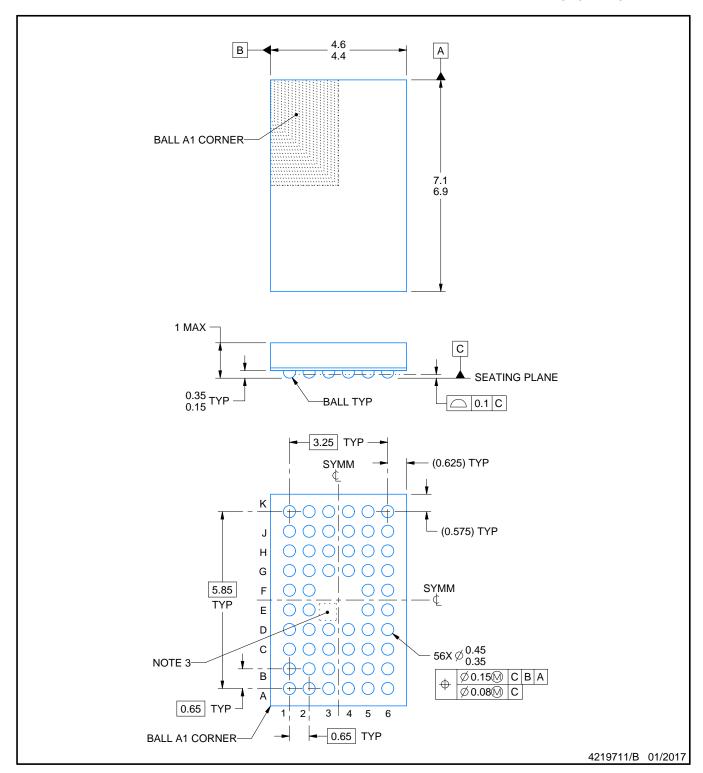
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



PLASTIC BALL GRID ARRAY



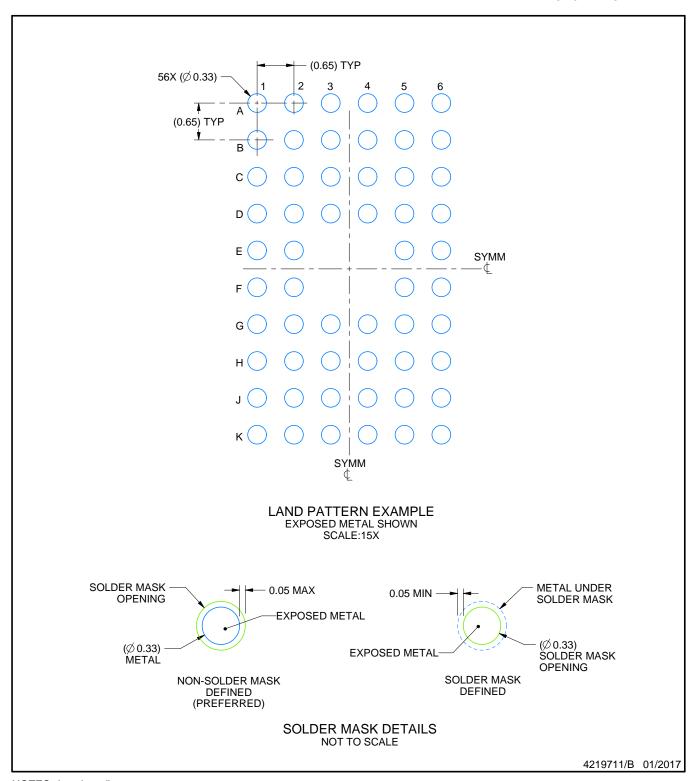
NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.
- 3. No metal in this area, indicates orientation.



PLASTIC BALL GRID ARRAY

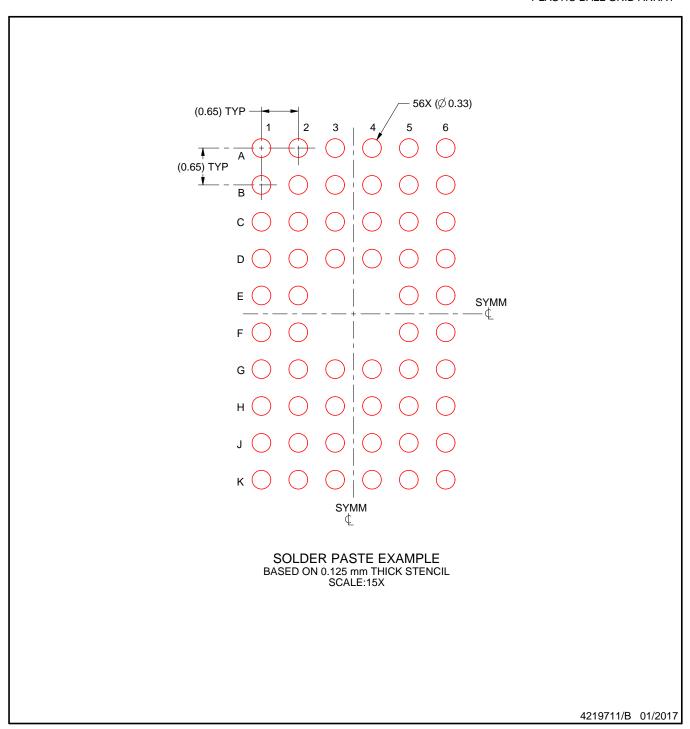


NOTES: (continued)

4. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 (www.ti.com/lit/spraa99).



PLASTIC BALL GRID ARRAY



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



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